PCN# : P69AAAB
Issue Date : Oct. 26, 2016

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local ON Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product :Jan. 24, 2017

Expected First Date Code of Changed Product :1705

Description of Change (From) :
Assembly Site:
WLCSP bump at sub-contractor Chipbond in Hsinchu, Taiwan
Change solder ball dimension from 120um
Change Ag content from 2.5%

Test and Die Processing Services (DPS) Site:
ATE Test and DPS at ON Semiconductor Penang, Malaysia.

Description of Change (To) :
Assembly Site:
WLCSP bump processing to Advanced Semiconductor Engineering Group (ASE) located in Kaohsiung, Taiwan
Change solder ball dimension to 129um
Change Ag content to 1.8%
Ball diameter change as detailed on the Marketing Outline specification UC006AHrev4.

Test Site:
ATE Test and DPS processing to ON Semiconductor located in Cebu, Philippines
No change to ATE test program

Reason for Change:
Consolidation of Manufacturing Facilities

Better quality and yield through equipment and facility upgrades.
- Increased automation in handling and inspection in assembly.

ON Semiconductor partnership with assembly subcontractors.
- Best manufacturing practices- access to many customers methods and practices.
- Advanced technology for fast ramp of future new products and technologies.

Affected Product(s):

FAN3850AUC16X		

FAN3850AUC16X – TSMC / ASE/Cebu package qualification data: PCN# P69AAAB

Qualification Plan	Device	Package	Process	No. of Lots
Q20150423	FAN3850AUC16X	UCEBU-A06	TSMC 0.18UM CMOS –ASE bump /Cebu DPS	3

Test Description:	Condition:	Standard :	Duration:	Results:
Highly Accelerated Stress Test	110C, 85%RH, 3.6V	JESD22-A110	264 hrs	0/231
Unbiased Highly Accelerated Stress Test	110C, 85%RH,	JESD22-A118	264 hrs	0/231
Temperature Cycle	-40C, 125C	JESD22-A104	850 Cycles	0/231